



SSC8L420GT8

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
40V	$\pm 20V$	2.6m Ω @10V	122A
		3.3m Ω @4.5V	

➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

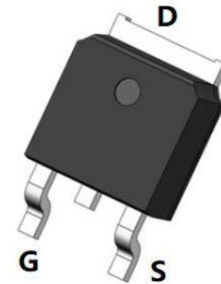
➤ Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

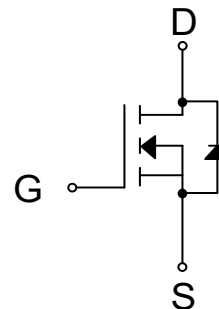
➤ Ordering Information

Device	Package	Shipping
SSC8L420GT8	TO-252-2L	2500/Reel

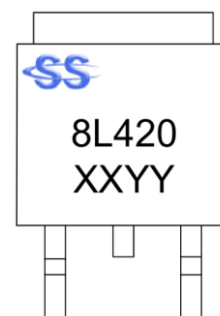
➤ Pin Configuration



TO-252-2L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		40	V
V_{GSS}	Gate-to-Source Voltage		± 20	V
I_{D}	Continuous Drain Current ^d	$T_{\text{C}}=25^{\circ}\text{C}$	122	A
		$T_{\text{C}}=100^{\circ}\text{C}$	68	
I_{DSM}	Continuous Drain Current ^a	$T_{\text{A}}=25^{\circ}\text{C}$	21	A
		$T_{\text{A}}=70^{\circ}\text{C}$	15	
I_{DM}	Pulsed Drain Current ^b		488	A
P_{D}	Power Dissipation ^c	$T_{\text{C}}=25^{\circ}\text{C}$	83	W
		$T_{\text{C}}=100^{\circ}\text{C}$	33	
P_{DSM}	Power Dissipation ^a	$T_{\text{A}}=25^{\circ}\text{C}$	2.5	W
		$T_{\text{A}}=70^{\circ}\text{C}$	1.6	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		32	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		256	mJ
T_{J}	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Max.	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance ^a	36	50	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	1.1	1.5	

Note:

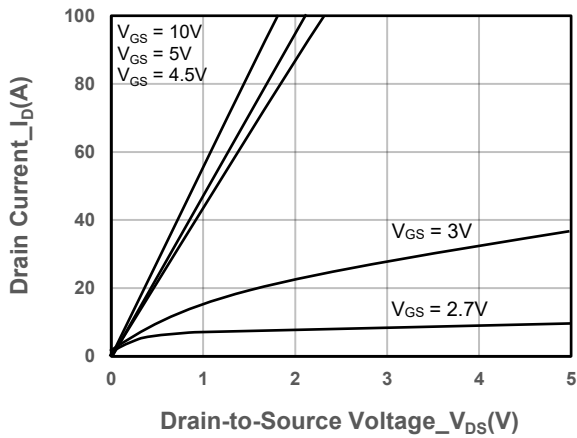
- The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_{D} is based on $T_{\text{J(MAX)}}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

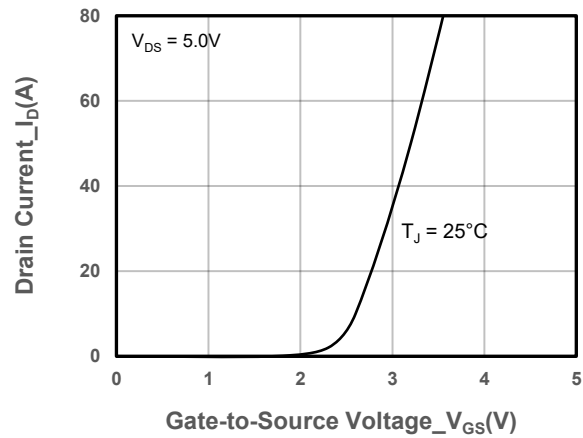
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1	1.5	2.0	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		2.6	3.5	mΩ
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 10A		3.3	4.5	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±200	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A		0.75	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.3		Ω
Input Capacitance	C _{ISS}	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz		2825		pF
Output Capacitance	C _{OSS}			670		
Reverse Transfer Capacitance	C _{RSS}			81		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 20V, I _D = 20A		57		nC
Gate to Source Charge	Q _{GS}			7.0		
Gate to Drain Charge	Q _{GD}			12		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 20V, R _L = 1Ω, R _G = 3Ω		8.8		ns
Rise Time	T _r			25		
Turn-off Delay Time	T _{D(OFF)}			41		
Fall Time	T _f			33		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=500A/us		45		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=500A/us		98		nC



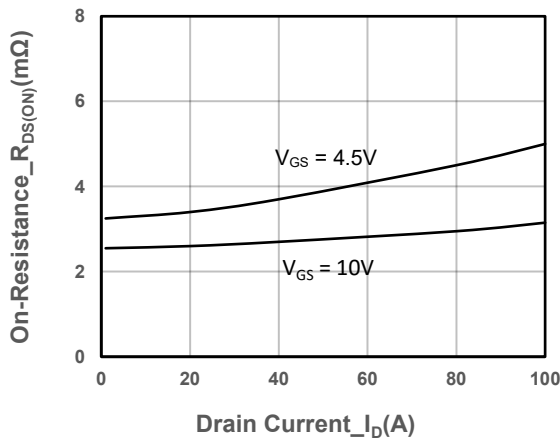
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



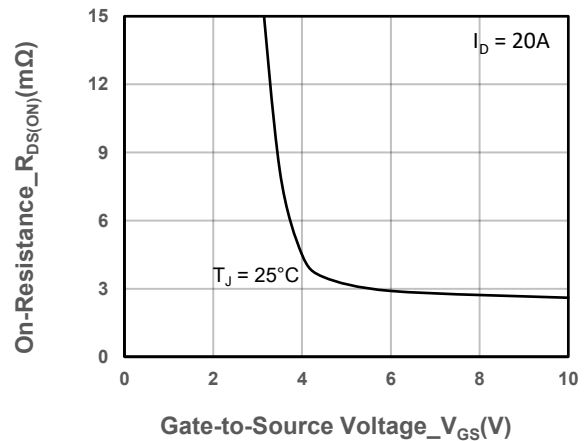
Output Characteristics



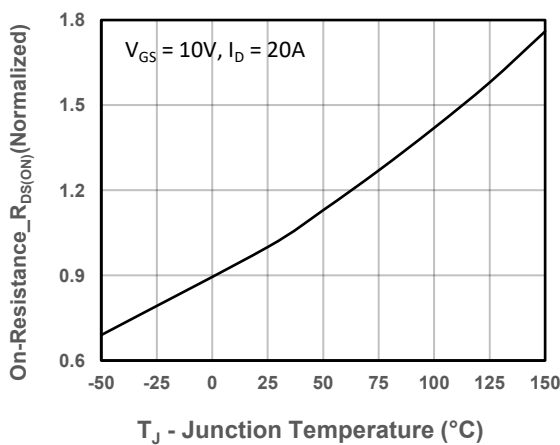
Transfer Characteristics



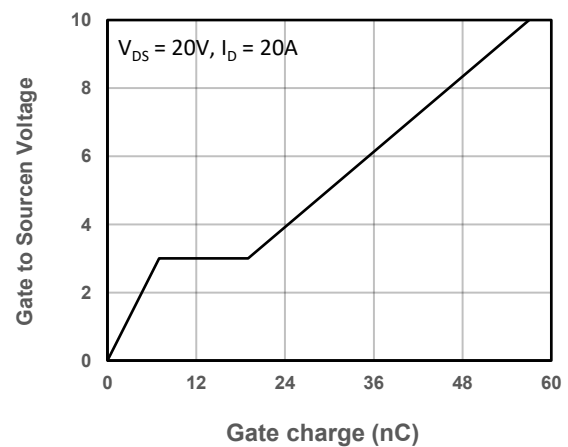
On-Resistance vs. Drain Current and Gate Voltage



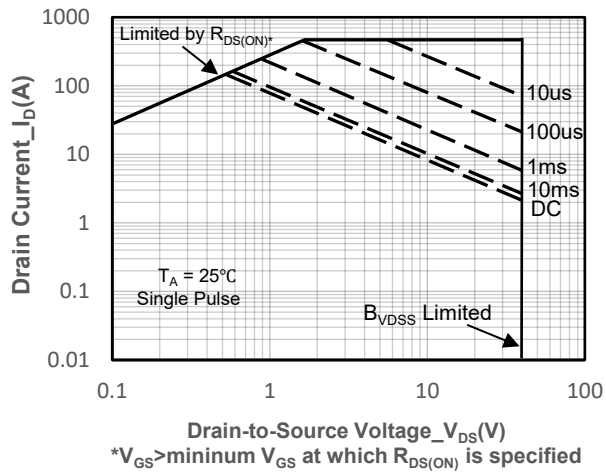
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

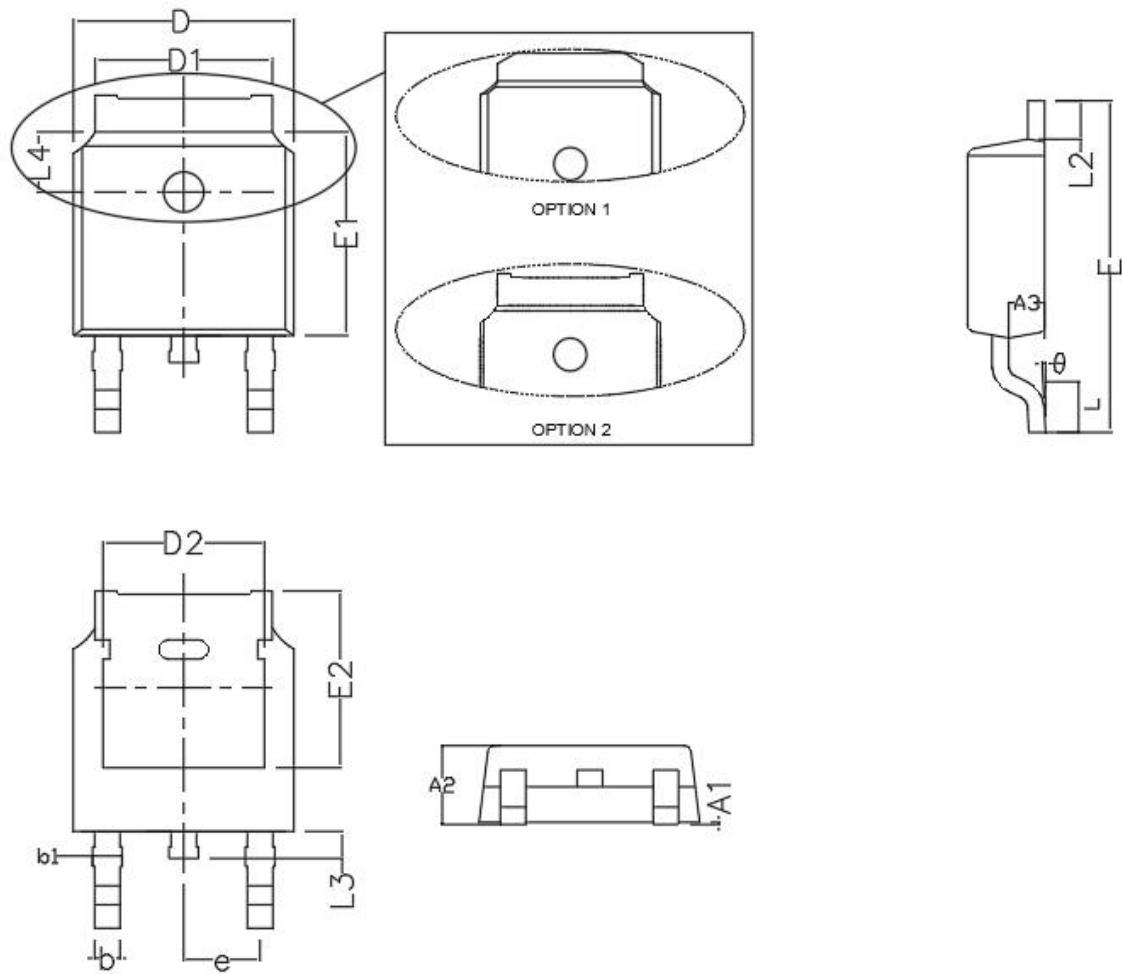


Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient

➤ Package Information



Symbol	MILL IMETER			Symbol	MILL IMETER		
	Min	Nom	Max		Min	Nom	Max
A1	0.000	/	0.200	E1	5.800	6.100	6.400
A2	2.100	2.300	2.500	E2	5.100	5.450	5.600
A3	0.900	1.040	1.170	e	2.286TYP		
b	0.600	0.762	0.910	L	1.270	1.500	2.032
b1	0.680	0.840	1.145	L2	0.900	1.100	1.270
D	6.300	6.600	6.900	L3	0.600	0.800	1.000
D1	4.950	5.330	5.700	L4	1.600	1.800	2.000
D2	4.315	4.830	5.230	θ	0°	/	10°
E	9.395	10.100	10.700				



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